

1-Bit Dual-Supply Level Translator

NL3V1T244, NL3V1T240, NL3V1T34

The NL3V1T244 / NL3V1T240 / NL3V1T34 are 1-bit configurable dual—supply level translators with 3-state outputs. The A– and B– ports are designed to track two different power supply rails, V_{CCA} and V_{CCB} respectively. Both supply rails are configurable from 0.9 V to 3.6 V allowing universal voltage level translation between the A– to B– ports.

The NL3V1T244 / NL3V1T34 are 1-bit level translators that allows non-inverting translations from A to B ports. The NL3V4T240 is a 1-bit level translator that allows inverting translations from A to B ports.

The output enable pin (\overline{OE}) , when High, disables all the output ports by putting them in 3-state. The \overline{OE} pin is designed to track V_{CCA} . The NL3V1T34 does not have an \overline{OE} pin.

Features

- Wide V_{CCA} and V_{CCB} Operating Range: 0.9 V to 3.6 V
- Balanced Output Drive: ±24 mA @ 3.0 V
- High-Speed w/ Balanced Propagation Delay: 2.8 ns max at 3.0 to 3.6 V
- Inputs Pins OVT to 3.6 V
- Non-preferential V_{CC} Sequencing
- Outputs at 3-State until Active V_{CC} is Reached
- Partial Power-Off Protection
- Outputs Switch to 3-State with either V_{CC} at GND
- Typical Max Data Rates:

380 Mbps (≥ 1.8 –V to 3.3–V Translation)

200 Mbps (≥1.1–V to [1.8–V, 2.5–V, 3.3–V] Translation)

150 Mbps (≥1.1–V to 1.5–V Translation)

100 Mbps (≥1.1-V to 1.2-V Translation)

• Small Pb-Free Packaging:

SC-88A, UDFN6

- –Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable*
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- Mobile Phones, PDAs, Other Portable Devices
- Automotive
- Industrial

MARKING DIAGRAMS



UDFN6 MU SUFFIX CASE 517AA





UDFN6 MU SUFFIX CASE 517AQ





SC-88A (SOT-353/SC-70) DF SUFFIX CASE 419A



XXX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

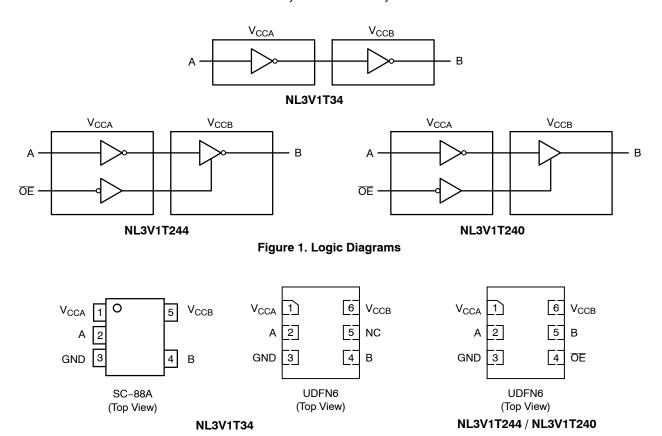


Figure 2. Pin Assignments (Top View)

FUNCTION TABLE

		OUTPUT				
INPUTS		NL3V1T34 NL3V1T244		NL3V1T240		
ŌĒ	A	В	В	В		
L	L	L	L	Н		
L	Н	Н	Н	L		
Н	Х	n/a	3-State	3-State		

PIN NAMES

PINS	DESCRIPTION			
Vcca	A Port DC Supply			
V _{ССВ}	B Port DC Supply			
GND	Ground			
Α	Input Port			
В	Output Port			
ŌĒ	Output Enable (Not available for NL3V1T34)			

Application Recommendations

During power-up and power-down, it is recommended that the \overline{OE} pin be connected to V_{CC} through pull-up resistors to ensure high impedance at the I/O ports.

MAXIMUM RATINGS

Symbol	Rating	Value	Condition	Unit
V _{CCA} , V _{CCB}	DC Supply Voltage	-0.5 to +4.3		V
VI	DC Input Voltage	-0.5 to +4.3		V
Vo	DC Output Voltage (Power Down Mode)	-0.5 to +4.3	V _{CCA} = V _{CCB} = 0	V
	(3-State Mode)	-0.5 to +4.3		
	(Active Mode)	-0.5 to V _{CCB} +0.5		
l _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C
$\theta_{\sf JA}$	Thermal Resistance (Note 1) SC-88A UDFN6		377 154	°C/W
P_{D}	Power Dissipation in Still Air SC-88A UDFN6		332 812	mW
MSL	Moisture Sensitivity Level		Level 1	-
F _R	Flammability Rating Oxygen Index: 28 to 34		UL 94 V-0 @ 0.125 in	-
V _{ESD}	ESD Withstand Voltage (Note 2) Human Body Model Charged Device Model		2 1	kV
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 25°C (Note 3)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
 HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued per JEDEC/JEP172A.
- 3. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CCA} , V _{CCB}	Positive DC Supply Voltage	0.9	3.6	V
VI	Input Voltage	GND	3.6	V
V _{IO}	Output Voltage (Power Down Mode)	GND	3.6	V
	(3-State Mode)	GND	3.6	
	(Active Mode)	GND	V _{CCB}	
T _A	Operating Temperature Range	-40	+125	°C
Δt / ΔV	Input Transition Rise or Rate	0	5	nS/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS - INPUT VOLTAGES

		Test Con-				-4	-40 °C to +85 °C		-40 °C to +125 °C				
Symbol	Parame- ter	di- tions	Port	V _{CCA} (V)	V _{CCB} (V)	Min	Typ (Note 4)	Max	Min	Max	Unit		
V _{IH}	Input HIGH		ŌĒ, A	2.7 – 3.6	0.9 - 3.6	2.0	_	-	2.0	-	V		
	Voltage			2.3 – 2.7		1.6	_	-	1.6	-			
							1.65-1.95		0.65 V _{CCA}	_	-	0.65 V _{CCA}	-
				1.1 – 1.6		0.7 V _{CCA}	_	_	0.7 V _{CCA}	_			
				0.9		-	0.9 V _{CCA}	-	_	-			
V_{IL}	Input LOW	ŌĒ, A	ŌĒ, A	2.7 – 3.6	0.9 - 3.6	-	-	0.8	-	0.8	V		
	Voltage			2.3 - 2.7		-	-	0.7	_	0.7			
				1.65-1.95		_	_	0.35 V _{CCA}	_	0.35 V _{CCA}			
				1.1 – 1.6		_	_	0.3 V _{CCA}	_	0.3 V _{CCA}			
				0.9		_	0.1 V _{CCA}	_	_	_			

^{4.} All typical values are at $T_A = 25^{\circ}C$.

DC ELECTRICAL CHARACTERISTICS - OUTPUT VOLTAGES

					-4	10 °C to +85 °	C	−40 °C to	+125 °C	
Symbol Paramete	Parameter	Test ter Conditions	V _{CCA} (V)	V _{CCB} (V)	Min	Typ (Note 4)	Max	Min	Max	Unit
V _{OH} Output HIGH	$V_I = V_{IH}$ or V_{IL} :				•				V	
	Voltage	$I_{OH} = -100 \mu A$	0.9	0.9	_	V _{CCB} – 0.1	-	-	-	
		1.1 – 3.6	1.1 – 3.6	V _{CCB} - 0.1	_	-	V _{CCB} - 0.1	-		
		$I_{OH} = -2 \text{ mA}$	1.1	1.1	0.85	-	-	0.85	-	1
		$I_{OH} = -6 \text{ mA}$	1.4	1.4	1.05	-	-	1.05	-	1
		$I_{OH} = -8 \text{ mA}$	1.65	1.65	1.2	-	-	1.2	-	1
		$I_{OH} = -12 \text{ mA}$	2.3	2.3	1.8	-	-	1.8	-	1
			2.7	2.7	2.2	-	-	2.2	-	1
		$I_{OH} = -18 \text{ mA}$	2.3	2.3	1.7	-	-	1.7	-	1
			3.0	3.0	2.4	-	-	2.4	-	1
		$I_{OH} = -24 \text{ mA}$	3.0	3.0	2.2	-	-	2.2	-	1
V _{OL}	Output LOW	$V_I = V_{IH}$ or V_{IL} :				•				V
	Voltage	I _{OL} = 100 μA	0.9	0.9	-	0.1	-	-	-	
			1.1 – 3.6	1.1 – 3.6	-	-	0.1	-	0.1	1
		I _{OL} = 2 mA	1.1	1.1	-	-	0.25	-	0.25	1
		I _{OL} = 6 mA	1.4	1.4	-	-	0.35	-	0.35	1
		I _{OL} = 8 mA	1.65	1.65	-	-	0.3	-	0.3	1
		I _{OL} = 12 mA	2.3	2.3	-	_	0.4	-	0.4	1
			2.7	2.7	-	-	0.4	-	0.4	1
		I _{OL} = 18 mA	2.3	2.3	-	-	0.4	-	0.4	
			3.0	3.0	-	-	0.4	-	0.4	
		I _{OL} = 24 mA	3.0	3.0	-	-	0.55	_	0.55	1

DC ELECTRICAL CHARACTERISTICS - LEAKAGE AND SUPPLY CURRENTS

		Test	V _{CCA}	V _{CCB}	-40 °C to	o +85 °C	–40 °C to	+125 °C	
Symbol	Parameter Conditions	(V)	(V)	Min	Max	Min	Max	Unit	
lı	Input Leakage Current	V _I = 3.6 V or GND	0.9 - 3.6	0.9 - 3.6	-	±1.0	-	±5.0	μΑ
l _{OZ}	3-State Output Leakage	$\overline{OE} = V_{IH}$; $V_O = GND$ to 3.6 V	3.6	3.6	-	±1.0	-	±5.0	μΑ
l _{OFF}	Power-Off Leakage	$V_1 \text{ or } V_0 = 0 \text{ to } 3.6 \text{ V}$ A	0	0.9 – 3.6	-	±1.0	-	±5.0	μΑ
	Current	В	0.9 - 3.6	0	-	±1.0	-	±5.0	
I _{CCA}	Quiescent Supply Current	$V_I = V_{CCA}$ or GND; $I_O = 0$	0.9 - 3.6	0.9 – 3.6	-	5.0	-	10	μΑ
		10 = 0	0	0.9 – 3.6	-	-1.0	-	-5.0	
			0.9 - 3.6	0	-	5.0	-	10	
I _{CCB}	Quiescent Supply Current	$V_I = V_{CCA}$ or GND;	0.9 - 3.6	0.9 – 3.6	-	5.0	-	10	μΑ
		I _O = 0	0	0.9 – 3.6	_	5.0	_	10	
			0.9 - 3.6	0	-	-1.0	-	-5.0	

NOTE: Connect ground before applying supply voltage V_{CCA} or V_{CCB} . This device is designed with the feature that the power-up sequence of V_{CCA} and V_{CCB} will not damage the IC.

AC ELECTRICAL CHARACTERISTICS (Notes 5 and 6)

				$T_A = -4$	10 °C to	+85 °C			T _A = -4	0 °C to	+125 °C		
			V _{CCB} (V)				V _{CCB} (V)						
			3.3	2.5	1.8	1.5	1.2	3.3	2.5	1.8	1.5	1.2	
Symbol	Parameter	V _{CCA} (V)	Max	Max	Max	Max	Max	Max	Max	Max	Max	Max	Unit
t _{PLH} ,	Propagation	3.3	2.9	3.3	4.5	5.6	9.3	3.3	3.8	5.0	6.2	9.5	nS
t _{PHL}	Delay, A to B	2.5	3.6	3.7	4.6	5.7	9.4	4.0	4.0	5.1	6.3	9.6	
		1.8	3.9	4.0	4.9	6.0	9.6	4.3	4.3	5.4	6.6	9.8	
	1.5	4.2	4.3	5.2	6.3	9.8	4.7	4.7	5.8	7.0	10.0		
		1.2	5.1	5.2	6.2	7.1	11.0	5.7	5.8	6.9	7.9	11.2	
t _{PZH} ,	Output Enable,	3.3	3.8	4.7	6.8	8.7	11.3	4.2	5.2	7.5	9.6	12.4	nS
t _{PZL}	OE to B	2.5	4.0	4.8	7.0	8.8	11.3	4.4	5.3	7.7	9.7	12.4	
		1.8	4.6	5.3	7.4	9.2	11.7	5.1	5.9	8.2	10.2	12.9	
		1.5	5.6	5.8	7.7	9.6	12.1	6.2	6.4	8.5	10.6	13.3	
		1.2	7.7	7.9	8.9	10.0	13.5	8.5	8.7	9.8	11.0	14.7	
t _{PHZ} ,	Output Disable,	3.3	6.2	6.4	8.1	9.3	10.2	6.9	7.1	9.0	10.3	11.3	nS
t _{PLZ}	OE to B	2.5	5.2	6.2	8.2	8.8	10.4	5.8	6.9	9.1	10.4	11.5	
		1.8	6.9	6.9	8.7	9.9	10.9	7.6	7.6	9.6	10.9	12.0	
		1.5	7.6	7.4	9.1	10.3	11.3	8.2	8.4	10.1	11.4	12.5	
		1.2	8.1	8.1	9.5	9.6	12.4	9.0	10.1	10.5	10.6	13.7	

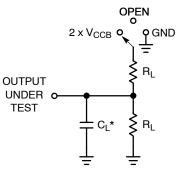
^{5.} Propagation delays defined per Figure 3.

CAPACITANCE

Symbol	Parameter	Test Conditions	Typ (Note 4)	Unit
C _{IN}	Control Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA}$	2.5	pF
C _{I/O}	I/O Pin Input Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA}$	5.0	pF
C _{PD} (Note 7)	Power Dissipation Capacitance	$V_{CCA} = V_{CCB} = 3.3 \text{ V}, V_I = 0 \text{ V or } V_{CCA}, f = 10 \text{ MHz}$	12	pF

^{7.} C_{PD} is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from: $I_{CC(operating)} \cong C_{PD} \times V_{CC} \times f_{IN} \times N_{SW}$ where $I_{CC} = I_{CCA} + I_{CCB}$ and $N_{SW} = total$ number of outputs switching.

^{6.} These parameters are guaranteed by characterization and are not production tested.



 $^{\star}C_{L}$ Includes probe and jig capacitance

Figure 3. AC Test Circuit

Test	Switch	C _L	R_L
t _{PLH} , t _{PHL}	OPEN	15 pF	2 kΩ
t_{PLZ} , t_{PZL}	2 x V _{CCB}		
t_{PHZ} , t_{PZH}	GND		

 C_L includes probe and jig capacitance

Pulse generator $Z_0 = 50 \Omega$

Input f = 1.0 MHz; $t_W = 500 \text{ ns}$

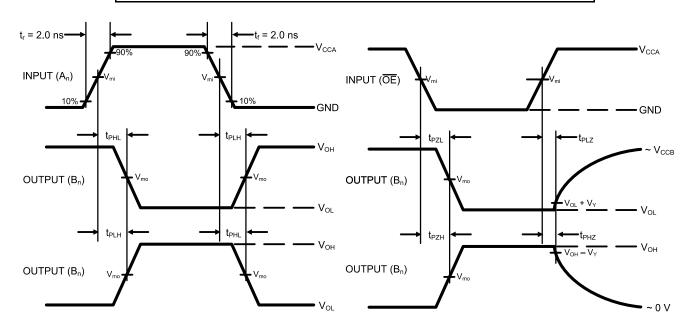


Figure 4. AC Waveforms

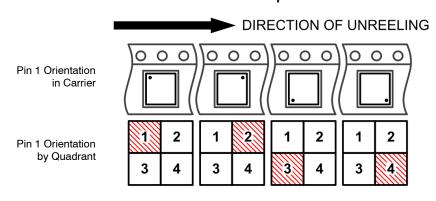
	V _{CC}							
Symbol	3.0 V – 3.6 V	2.3 V – 2.7 V	1.65 V – 1.95 V	1.4 V – 1.6 V	1.1 V – 1.3 V			
V _{mi}	V _{CCA} /2							
V _{mo}	V _{CCB} /2							
V _Y	0.3 V	0.15 V	0.15 V	0.1 V	0.1 V			

ORDERING INFORMATION

Device	Marking	Package	Pin 1 Quadrant	Shipping [†]
NL3V1T34DFT2G	AFR	SC-88A	3	3000 Units / Tape & Reel
NL3V1T34DFT2G-Q*	AFR	SC-88A	3	3000 Units / Tape & Reel
NL3V1T34MU1TAG	AD	UDFN6, 1.45x1, 0.5P	1	3000 Units / Tape & Reel
NL3V1T34MU1TCG	AD	UDFN6, 1.45x1, 0.5P	3	3000 Units / Tape & Reel
NL3V1T34MU2TBG	EQ	UDFN6, 1.2x1, 0.4P	2	3000 Units / Tape & Reel
NL3V1T244MU2TBG	AQ	UDFN6, 1.2x1, 0.4P	2	3000 Units / Tape & Reel
NL3V1T244MU2TBG-Q*	AQ	UDFN6, 1.2x1, 0.4P	2	3000 Units / Tape & Reel
NL3V1T240MU2TBG	A3	UDFN6, 1.2x1, 0.4P	2	3000 Units / Tape & Reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging

Pin 1 Orientation in Tape and Reel



Specifications Brochure, BRD8011/D.

–Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and PPAP Capable.

REVISION HISTORY

Revision	Description of Changes	Date
0	Initial document version release.	8/20/2025







SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

DATE 11 APR 2023

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS
- OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

DIM	MILLIMETERS		
INITU	MIN.	N□M.	MAX.
А	0.80	0.95	1.10
A1			0.10
A3	0.20 REF		
b	0.10	0.20	0.30
C	0.10		0.25
D	1.80	2.00	2,20
Е	2.00	2.10	2.20
E1	1.15	1.25	1.35
е	0.65 BSC		
L	0.10	0.15	0.30

- 419A-01 DBSDLETE, NEW STANDARD 419A-02
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS,

	L → -	
<u> </u>	0.50	5

5X b

→ 0.2 M B M

RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

5. COLLECTOR

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

= Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 2: PIN 1. ANODE 2. EMITTER 3. BASE 4. COLLECTOR 5. CATHODE	STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1	STYLE 4: PIN 1. SOURCE 1 2. DRAIN 1/2 3. SOURCE 1 4. GATE 1 5. GATE 2	STYLE 5: PIN 1. CATHODE 2. COMMON ANODE 3. CATHODE 2 4. CATHODE 3 5. CATHODE 4
STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR 5. COLLECTOR 2/BASE 1	STYLE 7: PIN 1. BASE 2. EMITTER 3. BASE 4. COLLECTOR 5. COLLECTOR	STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE 5. EMITTER	STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE	Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

DOCUMENT NUMBER:	98ASB42984B	Electronic versions are uncontrolled except when accessed directly from Printed versions are uncontrolled except when stamped "CONTROLLED	
DESCRIPTION:	N: SC-88A (SC-70-5/SOT-353)		PAGE 1 OF 1

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5. COLLECTOR 2/BASE 1



△ aaa C

UDFN6, 1.20x1.00x0.50, 0.40P CASE 517AA ISSUE E

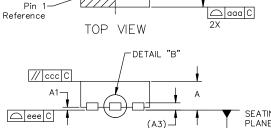
DATE 09 MAY 2025

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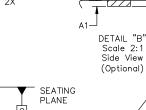
- 1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
- 2. CONTROLLING DIMENSION: MILLIMETERS.

Mold Compound

- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL.
- 4. COPLANARITY APPLIES TO TH EXPOSED PAD AS WELL AS THE TERMINALS.



D

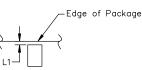


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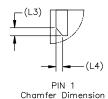
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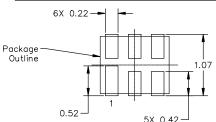
DETAIL "A"



DETAIL "A" Scale 2:1 Bottom View (Optional)



MILLIMETERS				
DIM	MIN	NOM	MAX	
А	0.45	0.50	0.55	
A1	0.00		0.05	
А3	(0.127 REF	-	
Ь	0.15	0.20	0.25	
D		1.20 BSC		
Ε		1.00 BSC		
е	0.40 BSC			
L	0.30 0.35 0.40			
L1	0.00		0.15	
L2	0.40	0.45	0.50	
L3	L3 0.14 REF			
L4 0.116 REF		-		
TOLER	ANCE FO	RM & PO	SITION	
aaa	0.10			
bbb	0.10			
ССС	0.10			
ddd	0.05			
eee		0.08		



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb—Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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L2			5X L
 -		ПП	Ţ
	6	4 - e	
6X b			
⊕ bbb C A B ddd C B	OTTO	M VIEW	

SIDE VIEW

GENERIC				
MARKING DIAGRAM*				
	XXM			

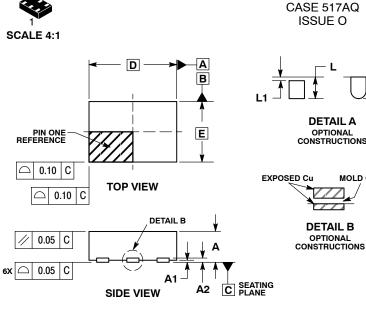
XX = Specific Device Code M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	UDFN6, 1.20x1.00x0.50, 0.40P		PAGE 1 OF 1	

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6X L

6X b

Ф

0.10 | C | A | B

0.05 C NOTE 3

е

UDFN6, 1.45x1.0, 0.5P CASE 517AQ **ISSUE 0**

DETAIL A OPTIONAL CONSTRUCTIONS

DETAIL B

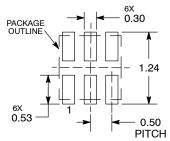
MOLD CMPD

DATE 15 MAY 2008

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS			
DIM	MIN MAX			
Α	0.45	0.55		
A1	0.00	0.05		
A2	0.07 REF			
b	0.20 0.30 1.45 BSC			
D				
Е	1.00 BSC			
е	0.50 BSC			
L	0.30 0.40			
L1	0.15			

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*

BOTTOM VIEW



Χ = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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